

# Failure Modes, Effects and Diagnostic Analysis

Project: ECHOTEL 961/962 Ultrasonic Single and Dual Point Level Switches

> Company: Magnetrol International, Inc. Aurora, IL USA

Contract Number: Q16/08-078 Report No.: MAG 16/08-078 R001 Version V1, Revision R3, December 20, 2016 Rudolf Chalupa



## Management Summary

This report summarizes the results of the hardware assessment in the form of a Failure Modes, Effects, and Diagnostic Analysis (FMEDA) of the ECHOTEL 961/962 Ultrasonic Single and Dual Point Level Switches, hardware revision and software revision per Section 2.5.1. A Failure Modes, Effects, and Diagnostic Analysis is one of the steps to be taken to achieve functional safety certification per IEC 61508 of a device. From the FMEDA, failure rates are determined. The FMEDA that is described in this report concerns only the hardware of the 961/962. For full functional safety certification purposes all requirements of IEC 61508 must be considered.

ECHOTEL 961/962 Ultrasonic Single and Dual Point Level Switches utilize pulsed signal technology to detect high, low, or dual point level in a broad range of liquid media applications. Model 961 is a single point level switch. Model 962 is a dual point switch used as a level controller or to control pumps in an auto-fill or auto-empty mode.

Table 1 gives an overview of the different versions that were considered in the FMEDA of the 961/962.

961 Dry Is Safe Single Point Level Switch, Reported Dry Condition Is Safe	
961 Wet Is Safe	Single Point Level Switch, Reported Wet Condition Is Safe
962 Dry Is Safe	Dual Point Level Switch, Reported Dry Condition Is Safe
962 Wet Is Safe	Dual Point Level Switch, Reported Wet Condition Is Safe

#### Table 1 Version Overview

The 961/962 is classified as a Type B<sup>1</sup> element according to IEC 61508, having a hardware fault tolerance of 0.

The analysis shows that the 961/962 has a Safe Failure Fraction between 90% and 99% (assuming that the logic solver is programmed to detect over-scale and under-scale currents) and therefore meets hardware architectural constraints for up to SIL 2 as a single device.

Based on the assumptions listed in 4.3, the failure rates for the 961/962 are listed in section 4.5.

These failure rates are valid for the useful lifetime of the product, see Appendix A.

The failure rates listed in this report are based on over 250 billion unit operating hours of process industry field failure data. The failure rate predictions reflect realistic failures and include site specific failures due to human events for the specified Site Safety Index (SSI), see section 4.2.2.

A user of the 961/962 can utilize these failure rates in a probabilistic model of a safety instrumented function (SIF) to determine suitability in part for safety instrumented system (SIS) usage in a particular safety integrity level (SIL).

<sup>&</sup>lt;sup>1</sup> Type B element: "Complex" element (using micro controllers or programmable logic); for details see 7.4.4.1.3 of IEC 61508-2, ed2, 2010.



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## 1 Purpose and Scope

This document shall describe the results of the hardware assessment in the form of the Failure Modes, Effects and Diagnostic Analysis carried out on the 961/962. From this, failure rates for each failure mode/category, useful life, and proof test coverage are determined.

The information in this report can be used to evaluate whether an element meets the average Probability of Failure on Demand ( $PFD_{AVG}$ ) requirements and if applicable, the architectural constraints / minimum hardware fault tolerance requirements per IEC 61508 / IEC 61511.

A FMEDA is part of the effort needed to achieve full certification per IEC 61508 or other relevant functional safety standard.



## 2 **Project Management**

## **2.1** *exida*

*exida* is one of the world's leading accredited Certification Bodies and knowledge companies, specializing in automation system safety cybersecurity, and availability with over 400 years of cumulative experience in functional safety. Founded by several of the world's top reliability and

safety experts from assessment organizations and manufacturers, *exida* is a global company with

offices around the world. *exida* offers training, coaching, project oriented system consulting services, safety lifecycle engineering tools, detailed product assurance, cyber-security and

functional safety certification, and a collection of on-line safety and reliability resources. *exida* maintains a comprehensive failure rate and failure mode database on process equipment based on 250 billion unit operating hours of field failure data.

## 2.2 Roles of the parties involved

Magnetrol International, Inc. Manufacturer of the 961/962

*exida* Performed the hardware assessment

Magnetrol International, Inc. contracted *exida* in August 2016 with the hardware assessment of the above-mentioned device.

## 2.3 Standards and literature used

The services delivered by *exida* were performed based on the following standards / literature.

[N1]	IEC 61508-2: ed2, 2010	Functional Safety of Electrical/Electronic/Programmable Electronic Safety-Related Systems
[N2]	Electrical Component Reliability Handbook, 4th Edition, 2017	<i>exida</i> LLC, Electrical Component Reliability Handbook, Fourth Edition, 2017
[N3]	Mechanical Component Reliability Handbook, 4th Edition, 2017	<i>exida</i> LLC, Electrical & Mechanical Component Reliability Handbook, Fourth Edition, 2017
[N4]	Goble, W.M. 2010	Control Systems Safety Evaluation and Reliability, 3 <sup>rd</sup> edition, ISA, ISBN 97B-1-934394-80-9. Reference on FMEDA methods
[N5]	IEC 60654-1:1993-02, second edition	Industrial-process measurement and control equipment – Operating conditions – Part 1: Climatic condition



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[N6]	O'Brien, C. & Bredemeyer, L., 2009	<i>exida</i> LLC., Final Elements & the IEC 61508 and IEC Functional Safety Standards, 2009, ISBN 978-1-9934977-01-9
[N7]	Scaling the Three Barriers, Recorded Web Seminar, June 2013,	Scaling the Three Barriers, Recorded Web Seminar, June 2013, http://www.exida.com/Webinars/Recordings/SIF-Verification-Scaling-the-Three-Barriers
[N8]	Meeting Architecture Constraints in SIF Design, Recorded Web Seminar, March 2013	http://www.exida.com/Webinars/Recordings/Meeting- Architecture-Constraints-in-SIF-Design
[N9]	Random versus Systematic – Issues and Solutions, September 2016	Goble, W.M., Bukowski, J.V., and Stewart, L.L., Random versus Systematic – Issues and Solutions, exida White Paper, PA: Sellersville, www.exida.com/resources/whitepapers, September 2016.
[N10]	Assessing Safety Culture via the Site Safety Index <sup>™</sup> , April 2016	Bukowski, J.V. and Chastain-Knight, D., Assessing Safety Culture via the Site Safety Index <sup>TM</sup> , Proceedings of the AIChE 12th Global Congress on Process Safety, GCPS2016, TX: Houston, April 2016.
[N11]	Quantifying the Impacts of Human Factors on Functional Safety, April 2016	Bukowski, J.V. and Stewart, L.L., Quantifying the Impacts of Human Factors on Functional Safety, Proceedings of the 12th Global Congress on Process Safety, AIChE 2016 Spring Meeting, NY: New York, April 2016.
[N12]	Criteria for the Application of IEC 61508:2010 Route 2H, December 2016	Criteria for the Application of IEC 61508:2010 Route 2H, exida White Paper, PA: Sellersville, www.exida.com, December 2016.
[N13]	Using a Failure Modes, Effects and Diagnostic Analysis (FMEDA) to Measure Diagnostic Coverage in Programmable Electronic Systems, November 1999	Goble, W.M. and Brombacher, A.C., Using a Failure Modes, Effects and Diagnostic Analysis (FMEDA) to Measure Diagnostic Coverage in Programmable Electronic Systems, Reliability Engineering and System Safety, Vol. 66, No. 2, November 1999.
[N14]	FMEDA – Accurate Product Failure Metrics, June 2015	Grebe, J. and Goble W.M., FMEDA – Accurate Product Failure Metrics, <u>www.exida.com</u> , June 2015.

## 2.4 *exida* tools used

exida FMEDA Tool	[T1] V7.1.18	<i>exida</i> FMEDA Tool
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## 2.5 Reference documents

## 2.5.1 Documentation provided by Magnetrol International, Inc.

[D1]	Doc # 51-646, Rev 4, 2015-	Instruction Manual
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		Cofety Manual
[D2]	Doc # 51-650, Rev 0, 2010- 07	Safety Manual
[D3]	Doc # 094-5047, Rev A, 2005-05	Schematic Drawing, 961
[D4]	Doc # 030-3590, Rev N, 2015-08-06	PCB Assembly Drawing & Bill of Material, 961
[D5]	Model 961 Theory of Operationdocx, 2016-09- 26	Theory of Operation
[D6]	961 HOUSING DRY IS SAFE.efm, 2013-06-26	FMEDA, 961 Housing, Dry Is Safe
[D7]	961 HOUSING WET IS SAFE.efm, 2013-06-26	FMEDA, 961 Housing, Wet Is Safe
[D8]	961 LOOP PC BOARD DRY IS SAFE.efm, 2013-06-26	FMEDA, 961 Loop PCB, Dry Is Safe
[D9]	961 LOOP PC BOARD WET IS SAFE.efm, 2013-06-26	FMEDA, 961 Loop PCB, Wet Is Safe
[D10]	Echotel_961 Loop SIL Summary.xlsx, 2016- 09-26	FMEDA Summary, Echotel 961
[D11]	Doc # 094-5050, Rev C, 2006-10	Schematic Drawing, 962
[D12]	Doc # 030-3590, Rev N, 2015-08-06	PCB Assembly Drawing & Bill of Material, 962
[D13]	962 LOOP PC BOARD DRY IS SAFE DELAY IS SAFE.efm, 2013- 07-25	FMEDA, 962 Loop PCB, Dry Is Safe
[D14]	962 LOOP PC BOARD WET IS SAFE DELAY IS SAFE.efm.efm, 2013-07-25	FMEDA, 962 Loop PCB, Wet Is Safe
[D15]	Echotel-962 Loop SIL Summary.xlsx, 2016- 09-26	FMEDA Summary, Echotel 962
[D16]	961 FMEDA REVIEW NOTESwithComments.docx , 2016-10-10	Failure Modes, Effects, and Diagnostic Analysis - Review Notes –961/962
[D17]	961 LOOP PC	FMEDA, 961 Loop PCB, Dry Is Safe



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	BOARD DRY IS SAFEwithCorrections.efm, 2013-10-10	
[D18]	961 LOOP PC BOARD WET IS SAFEwithCorrections.efm.e fm, 2013-10-10	FMEDA, 961 Loop PCB, Wet Is Safe
[D19]	Echotel_961 Loop SIL SummaryWithCorrections.xl sx, 2016-10-10	FMEDA Summary, Echotel 961
[D20]	962 LOOP PC BOARD DRY IS SAFE DELAY IS SAFEwithCorrections.efm, 2013-10-10	FMEDA, 962 Loop PCB, Dry Is Safe
[D21]	962 LOOP PC BOARD WET IS SAFE DELAY IS SAFEwithCorrections.efm, 2013-10-10	FMEDA, 962 Loop PCB, Wet Is Safe
[D22]	Echotel-962 Loop SIL SummaryWithCorrections.xl sx, 2016-10-10	FMEDA Summary, Echotel 962

## 2.5.2 Documentation generated by *exida*

[R1]	961 HOUSING DRY IS SAFE RPC 2016-10-03.xls	FMEDA, 961 Housing, Dry Is Safe
[R2]	961 HOUSING WET IS SAFE RPC 2016-10-03.xls	FMEDA, 961 Housing, Wet Is Safe
[R3]	961 LOOP PC BOARD DRY IS SAFE RPC 2016- 10-03.xls	FMEDA, 961 Loop PCB, Dry Is Safe
[R4]	961 FMEDA REVIEW NOTES.docx, 2016-10-04	Failure Modes, Effects, and Diagnostic Analysis - Review Notes –961/962



## **3 Product Description**

ECHOTEL 961/962 Ultrasonic Single and Dual Point Level Switches utilize pulsed signal technology to detect high, low, or dual point level in a broad range of liquid media applications. Model 961 is a single point level switch. Model 962 is a dual point switch used as a level controller or to control pumps in an auto-fill or auto-empty mode.961/962 switches utilize ultrasonic energy to detect the presence or absence of liquid in a single or dual point transducer. Ultrasonic contact level technology uses high frequency sound waves that are easily transmitted across a transducer gap in the presence of a liquid media, but are attenuated when the gap is dry. Model 961/962 switches use an ultrasonic frequency of 2 MHz to perform this liquid level measurement in a wide variety of process media and application conditions.

The transducer uses a pair of piezoelectric crystals that are encapsulated in epoxy at the tip of the transducer. The crystals are made of a ceramic material that vibrates at a given frequency when subjected to an applied voltage. The transmit crystal converts the applied voltage from the electronics into an ultrasonic signal. When liquid is present in the gap, the receive crystal senses the ultrasonic signal from the transmit crystal and converts it back to an electrical signal. This signal is sent to the electronics to indicate the presence of liquid in the transducer gap. When there is no liquid present, the ultrasonic signal is attenuated and is not detected by the receive crystal.





### Figure 1 961/962, Parts included in the FMEDA

Table 2 gives an overview of the different versions that were considered in the FMEDA of the 961/962.

### **Table 2 Version Overview**

961 Dry Is Safe	Single Point Level Switch, Reported Dry Condition Is Safe
961 Wet Is Safe	Single Point Level Switch, Reported Wet Condition Is Safe
962 Dry Is Safe	Dual Point Level Switch, Reported Dry Condition Is Safe
962 Wet Is Safe	Dual Point Level Switch, Reported Wet Condition Is Safe

The 961/962 is classified as a Type  $B^2$  element according to IEC 61508, having a hardware fault tolerance of 0.

<sup>&</sup>lt;sup>2</sup> Type B element: "Complex" element (using micro controllers or programmable logic); for details see 7.4.4.1.3 of IEC 61508-2, ed2, 2010.



## 4 Failure Modes, Effects, and Diagnostic Analysis

The Failure Modes, Effects, and Diagnostic Analysis was performed based on the documentation in section 2.5.1 and is documented in [R1] to [R4].

When the effect of a certain failure mode could not be analyzed theoretically, the failure modes were introduced on component level and the effects of these failure modes were examined on system level, see Fault Injection Test Report (included in each client FMEDA).

## 4.1 Failure categories description

In order to judge the failure behavior of the 961/962, the following definitions for the failure of the device were considered.

Fail-Safe State	Failure that deviates the process signal or the actual output by more than 2% of span, drifts toward the user defined threshold (Trip Point) and that leaves the output within the active scale.
Fail Safe	Failure that causes the device to go to the defined fail-safe state without a demand from the process.
Fail Detected	Failure that causes the output signal to go to the predefined alarm state (3.6 or 22 mA, user selectable).
Fail Dangerous	Failure that deviates the process signal or the actual output by more than 2% of span, drifts away from the user defined threshold (Trip Point) and that leaves the output within the active scale.
Fail Dangerous Undetected	Failure that is dangerous and that is not being diagnosed by automatic diagnostics.
Fail Dangerous Detected	Failure that is dangerous but is detected by automatic diagnostics.
Fail High	Failure that causes the output signal to go to the over-range or high alarm output current (> 21 mA).
Fail Low	Failure that causes the output signal to go to the under-range or low alarm output current (< 3.6 mA).
No Effect	Failure of a component that is part of the safety function but that has no effect on the safety function.
Annunciation Detected	Failure that does not directly impact safety but does impact the ability to detect a future fault (such as a fault in a diagnostic circuit) and that is detected by internal diagnostics. A Fail Annunciation Detected failure leads to a false diagnostic alarm.
Annunciation Undetected	Failure that does not directly impact safety but does impact the ability to detect a future fault (such as a fault in a diagnostic circuit) and that is not detected by internal diagnostics.

The failure categories listed above expand on the categories listed in IEC 61508 in order to provide a complete set of data needed for design optimization.



Depending on the application, a Fail High or a Fail Low failure can either be safe or dangerous and may be detected or undetected depending on the programming of the logic solver. Consequently, during a Safety Integrity Level (SIL) verification assessment the Fail High and Fail Low failure categories need to be classified as safe or dangerous, detected or undetected.

The Annunciation failures are provided for those who wish to do reliability modeling more detailed than required by IEC61508. It is assumed that the probability model will correctly account for the Annunciation failures.

## 4.2 Methodology – FMEDA, failure rates

### 4.2.1 FMEDA

A FMEDA (Failure Mode Effect and Diagnostic Analysis) is a failure rate prediction technique based on a study of design strength versus operational profile stress. It combines design FMEA techniques with extensions to identify automatic diagnostic techniques and the failure modes relevant to safety instrumented system design. It is a technique recommended to generate failure rates for each failure mode category [N13, N14].

### 4.2.2 Failure rates

The accuracy of any FMEDA analysis depends upon the component reliability data as input to the process. Component data from consumer, transportation, military or telephone applications could generate failure rate data unsuitable for the process industries. The component data used by

*exida* in this FMEDA is from the Electrical and Mechanical Component Reliability Handbooks [N3] which were derived using over 250 billion unit operational hours of process industry field failure data from multiple sources and failure data formulas from international standards. The component failure rates are provided for each applicable operational profile and application, see Appendix C.

The *exida* profile chosen for this FMEDA was 2, judged to be the best fit for the product and application information submitted by Magnetrol International, Inc.. It is expected that the actual number of field failures will be less than the number predicted by these failure rates.

Early life failures (infant mortality) are not included in the failure rate prediction as it is assumed that some level of commission testing is done. End of life failures are not included in the failure rate prediction as useful life is specified.

The failure rates are predicted for a Site Safety Index of SSI=2 [N10, N11] as this level of operation is common in the process industries. Failure rate predictions for other SSI levels are included in the exSILentia® tool from exida.

The user of these numbers is responsible for determining the failure rate applicability to any

particular environment. *exida* Environmental Profiles listing expected stress levels can be found in Appendix C. Some industrial plant sites have high levels of stress. Under those conditions the failure rate data is adjusted to a higher value to account for the specific conditions of the plant. exida has detailed models available to make customized failure rate predictions. Contact exida.

Accurate plant specific data may be used to check validity of this failure rate data. If a user has

data collected from a good proof test reporting system such as *exida* SILStat<sup>™</sup> that indicates higher failure rates, the higher numbers shall be used.



## 4.3 Assumptions

The following assumptions have been made during the Failure Modes, Effects, and Diagnostic Analysis of the 961/962.

- The worst case assumption of a series system is made. Therefore only a single component failure will fail the entire 961/962 and propagation of failures is not relevant.
- Failure rates are constant for the useful life period.
- Any product component that cannot influence the safety function (feedback immune) is excluded. All components that are part of the safety function including those needed for normal operation are included in the analysis.
- The stress levels are specified in the *exida* Profile used for the analysis are limited by the manufacturer's published ratings.
- Practical fault insertion tests have been used when applicable to demonstrate the correctness of the FMEDA results.
- The HART protocol is only used for setup, calibration, and diagnostics purposes, not for safety critical operation.
- The application program in the logic solver is constructed in such a way that Fail High and Fail Low failures are detected regardless of the effect, safe or dangerous, on the safety function.
- Materials are compatible with process conditions.
- The device is installed and operated per manufacturer's instructions.
- External power supply failure rates are not included.
- Worst-case internal fault detection time is 10 seconds.

### 4.4 Application specific restrictions

The following application specific restrictions are applicable to the 961/962 and have been considered during the Failure Modes, Effects, and Diagnostic Analysis of the 961/962. These restrictions shall be included in the safety manual for the 961/962.

• The safety function must be designed so that it will operate correctly with the 961/962 set to maximum delay.

### 4.5 Results

Using reliability data extracted from the *exida* Electrical and Mechanical Component Reliability Handbook the following failure rates resulted from the 961/962 FMEDA.



#### Table 3 Failure rates 961 Dry Is Safe

Failure Category	Failure Rate	Failure Rate (FIT)	
Fail Safe Undetected	38		
Fail Dangerous Detected	234		
Fail Detected (detected by internal diagnostics)	190		
Fail High (detected by logic solver)18			
Fail Low (detected by logic solver)	26		
Fail Dangerous Undetected		10	
No Effect	118		
Annunciation Undetected	15		

### Table 4 Failure rates 961 Wet Is Safe

Failure Category	ire Category Failure Rate (FI1	
Fail Safe Undetected		20
Fail Dangerous Detected	234	
Fail Detected (detected by internal diagnostics)	190	
Fail High (detected by logic solver)	18	
Fail Low (detected by logic solver)	26	
Fail Dangerous Undetected		27
No Effect		118
Annunciation Undetected	15	



#### Table 5 Failure rates 962 Dry Is Safe

Failure Category	Failure Rate (FIT)	
Fail Safe Undetected		64
Fail Dangerous Detected	426	
Fail Detected (detected by internal diagnostics)	373	
Fail High (detected by logic solver)22		
Fail Low (detected by logic solver)	31	
Fail Dangerous Undetected		10
No Effect	124	
Annunciation Undetected	7	

#### Table 6 Failure rates 962 Wet Is Safe

Failure Category Failure F		(FIT)
Fail Safe Undetected		26
Fail Dangerous Detected	426	
Fail Detected (detected by internal diagnostics)	373	
Fail High (detected by logic solver)	22	
Fail Low (detected by logic solver)	31	
Fail Dangerous Undetected		47
No Effect	124	
Annunciation Undetected	7	

These failure rates are valid for the useful lifetime of the product, see Appendix A.

According to IEC 61508 the architectural constraints of an element must be determined. This can be done by following the  $1_{H}$  approach according to 7.4.4.2 of IEC 61508 or the  $2_{H}$  approach according to 7.4.4.3 of IEC 61508 (see Section 5.2).

The  $1_H$  approach involves calculating the Safe Failure Fraction for the entire element.

The  $2_H$  approach involves assessment of the reliability data for the entire element according to 7.4.4.3.3 of IEC 61508.

The analysis shows that the 961/962 has a Safe Failure Fraction between 60% and 90% (assuming that the logic solver is programmed to detect over-scale and under-scale currents) and therefore meets hardware architectural constraints for up to SIL 2 as a single device.

Table 7 lists the failure rates for the 961/962 according to IEC 61508.



### Table 7 Failure rates according to IEC 61508 in FIT

Device	$\lambda_{\text{SD}}$	$\lambda_{SU}{}^3$	$\lambda_{DD}$	λ <sub>DU</sub>	SFF⁴
961 Dry Is Safe	0	38	234	10	96.5%
961 Wet Is Safe	0	20	234	27	90.4%
962 Dry Is Safe	0	64	426	10	98.0%
962 Wet Is Safe	0	26	426	47	90.6%

<sup>&</sup>lt;sup>3</sup> It is important to realize that the No Effect failures are no longer included in the Safe Undetected failure category according to IEC 61508, ed2, 2010.

Safe Failure Fraction if needed, is to be calculated on an element level



#### 5 Using the FMEDA Results

The following section(s) describe how to apply the results of the FMEDA.

#### 5.1 PFD<sub>avg</sub> calculation 961/962

Using the failure rate data displayed in section 4.5, and the failure rate data for the associated element devices, an average the Probability of Failure on Demand (PFD<sub>avg</sub>) calculation can be performed for the element.

Probability of Failure on Demand (PFD<sub>avo</sub>) calculation uses several parameters, many of which are determined by the particular application and the operational policies of each site. Some parameters are product specific and the responsibility of the manufacturer. Those manufacturer specific parameters are given in this third party report.

Probability of Failure on Demand (PFD<sub>avg</sub>) calculation is the responsibility of the owner/operator of a process and is often delegated to the SIF designer. Product manufacturers can only provide a PFD<sub>avg</sub> by making many assumptions about the application and operational policies of a site. Therefore, use of these numbers requires complete knowledge of the assumptions and a match with the actual application and site.

Probability of Failure on Demand (PFD<sub>avg</sub>) calculation is best accomplished with exida's exSILentia tool. See Appendix D for a complete description of how to determine the Safety Integrity Level for an element. The mission time used for the calculation depends on the PFD<sub>avd</sub> target and the useful life of the product. The failure rates and the proof test coverage for the element are required to perform the PFD<sub>avg</sub> calculation. The proof test coverages for the suggested proof test are listed in Appendix B.

#### 5.2 exida Route 2<sub>H</sub> Criteria

IEC 61508, ed2, 2010 describes the Route  $2_{\rm H}$  alternative to Route  $1_{\rm H}$  architectural constraints. The standard states:

"based on data collected in accordance with published standards (e.g., IEC 60300-3-2: or ISO 14224); and, be evaluated according to

- the amount of field feedback; and •
- the exercise of expert judgment; and when needed
- the undertake of specific tests,

in order to estimate the average and the uncertainty level (e.g., the 90% confidence interval or the probability distribution) of each reliability parameter (e.g., failure rate) used in the calculations."

*exida* has interpreted this to mean not just a simple 90% confidence level in the uncertainty analysis, but a high confidence level in the entire data collection process. As IEC 61508, ed2, 2010

does not give detailed criteria for Route  $2_{H}$ , *exida* has established the following:

1. field unit operational hours of 100,000,000 per each component; and

2. a device and all of its components have been installed in the field for one year or more; and

3. operational hours are counted only when the data collection process has been audited for correctness and completeness; and



4. failure definitions, especially "random" vs. "systematic" [N9] are checked by *exida*; and 5. every component used in an FMEDA meets the above criteria.

This set of requirements is chosen to assure high integrity failure data suitable for safety integrity verification. [N12]



# 6 Terms and Definitions

Automatic Diagnostics	Tests performed online internally by the device or, if specified, externally by another device without manual intervention.
<i>exida</i> criteria	A conservative approach to arriving at failure rates suitable for use in hardware evaluations utilizing the 2 <sub>H</sub> Route in IEC 61508-2.
Fault tolerance	Ability of a functional unit to continue to perform a required function in the presence of faults or errors (IEC 61508-4, 3.6.3).
FIT	Failure in Time (1x10 <sup>-9</sup> failures per hour)
FMEDA	Failure Mode Effect and Diagnostic Analysis
HFT	Hardware Fault Tolerance
PFD <sub>avg</sub>	Average Probability of Failure on Demand
SFF	Safe Failure Fraction, summarizes the fraction of failures which lead to a safe state plus the fraction of failures which will be detected by automatic diagnostic measures and lead to a defined safety action.
SIF	Safety Instrumented Function
SIL	Safety Integrity Level
SIS	Safety Instrumented System – Implementation of one or more Safety Instrumented Functions. A SIS is composed of any combination of sensor(s), logic solver(s), and final element(s).
Type A element	"Non-Complex" element (using discrete components); for details see 7.4.4.1.2 of IEC 61508-2
Type B element	"Complex" element (using complex components such as micro controllers or programmable logic); for details see 7.4.4.1.3 of IEC 61508-2



## 7 Status of the Document

## 7.1 Liability

exida prepares FMEDA reports based on methods advocated in International standards. Failure

rates are obtained from a collection of industrial databases. *exida* accepts no liability whatsoever for the use of these numbers or for the correctness of the standards on which the general calculation methods are based.

Due to future potential changes in the standards, product design changes, best available information and best practices, the current FMEDA results presented in this report may not be fully consistent with results that would be presented for the identical model number product at some

future time. As a leader in the functional safety market place, *exida* is actively involved in evolving best practices prior to official release of updated standards so that our reports effectively anticipate any known changes. In addition, most changes are anticipated to be incremental in nature and results reported within the previous three-year period should be sufficient for current usage without significant question.

Most products also tend to undergo incremental changes over time. If an *exida* FMEDA has not been updated within the last three years, contact the product vendor to verify the current validity of the results.

### 7.2 Releases

Version History: V1, R3: Updated per further client feedback, latest exida template, 2016-12-20 V1, R2: Updated per client feedback, 2016-11-18

V1, R1: Released to Magnetrol International, Inc.; 2016-10-17

V0, R1: Draft; 2016-10-10

Author(s): Rudolf Chalupa

Review: V0, R1: Ted Stewart (*exida*); 10/17/16

V1, R2: John Benway (Magnetrol International, Inc.); 2016-11-22

Release Status: Released to Magnetrol International, Inc.

### 7.3 Future enhancements

At request of client.



## 7.4 Release signatures

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Ted Stewart, CFSP, Safety Engineer



## Appendix A Lifetime of Critical Components

According to section 7.4.9.5 of IEC 61508-2, a useful lifetime, based on experience, should be determined and used to replace equipment before the end of useful life.

Although a constant failure rate is assumed by the exida FMEDA prediction method (see section 4.2.2) this only applies provided that the useful lifetime<sup>5</sup> of components is not exceeded. Beyond their useful lifetime the result of the probabilistic calculation method is likely optimistic, as the probability of failure significantly increases with time. The useful lifetime is highly dependent on the subsystem itself and its operating conditions.

Table 8 shows which components are contributing to the dangerous undetected failure rate and therefore to the PFD<sub>avg</sub> calculation and what their estimated useful lifetime is.

### Table 8 Useful lifetime of components contributing to dangerous undetected failure rate

Component	Useful Life
Capacitor (electrolytic) - Tantalum electrolytic, solid electrolyte	Approx. 500,000 hours

It is the responsibility of the end user to maintain and operate the 961/962 per manufacturer's instructions. Furthermore, regular inspection should show that all components are clean and free from damage.

The limiting factors with regard to the useful lifetime of the system are the tantalum electrolytic capacitors. Therefore the useful is predicted to be 50 years.

When plant experience indicates a shorter useful lifetime than indicated in this appendix, the number based on plant experience should be used.

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<sup>&</sup>lt;sup>5</sup> Useful lifetime is a reliability engineering term that describes the operational time interval where the failure rate of a device is relatively constant. It is not a term which covers product obsolescence, warranty, or other commercial issues.



## Appendix B Proof Tests to Reveal Dangerous Undetected Faults

According to section 7.4.5.2 f) of IEC 61508-2 proof tests shall be undertaken to reveal dangerous faults which are undetected by automatic diagnostic tests. This means that it is necessary to specify how dangerous undetected faults which have been noted during the Failure Modes, Effects, and Diagnostic Analysis can be detected during proof testing.

## B.1 Suggested Proof Test

The suggested proof test for the 961/962 is described below. Refer to the table in B.2 for the Proof Test Coverages

### Table 9 Suggested Proof Test, 961

Step	Proof Test, Echotel Model 961 Loop				
``	(Refer to the Model 961 installation and operation manual and the SIL Safety Manual. Note the chart in the High/Low Dip Switch section of the I & O Manual.)				
1	Bypass the PLC or take other action to avoid a false trip.				
2	Inspect the Unit in detail outside and inside for physical damage or evidence of environmental or process leaks.				
	a. Inspect the exterior of the Unit housing. If there is any evidence of physical damage that may impact the integrity of the housing and the environmental protection, the unit should be repaired or replaced.				
	b. Inspect the interior of the Unit. Any evidence of moisture, from process or environment, is an indication of housing damage, and the unit should be repaired or replaced.				
3	Observe and record the settings of the HI/LOW and 22/3.6 DIP switches, the LED indicators, Loop Current and Sensor GAP condition (WET or DRY).				
	If the FAULT LED is lighted, diagnose the fault and repair or replace the unit.				
	Confirm proper operation of the unit: WET/DRY GAP condition; 8mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA or 16mA +/- 1 mA.				
	a. Press LOOP TEST push button and confirm change; 8mA >> 16mA or 16mA >> 8mA . Release the button and unit returns to proper operation.				
	b. Change HI/LOW DIP switch position. Confirm both LED & Loop Current change state; 8mA >> 16mA or 16mA >> 8mA. Observe and record the time delay from change of DIP switch until LED and Loop current change. Delay is set by Time Delay Pot, so the delay may take somewhere around 10 seconds. Change HI/LOW DIP switch back to original setting and				
	confirm proper operation, after the delay.c.Press FAULT TEST push button and confirm: FAULT LED lights; Loopcurrent ≥ 22mA or ≤ 3.6mA based on 22/3.6 switch. Release button.				



	d. Change the 22/3.6 DIP switch position. Press FAULT TEST push button and confirm: FAULT LED lights; Loop current $\ge$ 22mA or $\le$ 3.6mA as expected. Release push button. Return 22/3.6 switch to original setting.
	e. Adjust the Time Delay Pot to maximum delay, fully clock-wise up to 25 turns. Change HI/LOW DIP switch position and observe the time delay from change of DIP switch until LED and Loop current change. Confirm delay is ~10 seconds. Change HI/LOW DIP switch back to original setting and confirm ~10 seconds delay. Adjust the Time Delay Pot to minimum delay, fully counter-clock-wise ~25 turns. Change HI/LOW DIP switch position and observe the time delay. Confirm delay ≤ 1 second. Change HI/LOW DIP switch back to original setting and confirm switch back to original setting and confirm delay.
4	When possible moving the process level will provide a more complete proof test.
	Confirm proper operation of the unit: WET/DRY GAP condition; 8mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA or 16mA +/- 1 mA.
	a. Move the process level and confirm the GAP condition has changed. Confirm proper operation of the unit: WET/DRY GAP condition; 8mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA or 16mA +/- 1 mA.
	b. Move the process level and confirm the GAP condition has returned to orginal state. Confirm proper operation of the unit: WET/DRY GAP condition; 8mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA or 16mA +/- 1 mA.
	c. If unit fails the tests of steps 4.a or 4.b proceed to step 5.
	<ul> <li>Adjust the Time Delay Pot to the original setting recorded in step 3b.</li> <li>Use HI/LOW DIP switch (just as you did in step 3b) to confirm that delay is returned to original setting.</li> </ul>
	e. Proceed to step 6.
5	If the unit under test fails to respond to process level changes remove the unit from the process and bench test.
	a. Remove the unit from the process. Inspect the ultrasound transducer for evidence of damage or coating buildup. Fouling on the transducer surface may interfere with normal operation. If heavy fouling is evident, it is suggested to service the transducer more frequently.
	b. Clean the ultrasonic transducer, especially in the area of the sensor GAP.
	c. Perform a bench test per the steps of section 4. When possible it is best to use the actual process material, because material properties affect the
	ultrasonic performance. Confirm proper unit operation: WET/DRY GAP condition; 8mA LED or 16mA LED is lighted; Loop current = $8mA +/- 1mA$ or $16mA +/- 1 mA$ .
	d. If unit passes the tests of steps 5.c, return to the process installation and repeat the tests of step 4.
	e. If the unit fails re-test in the process, it must be replaced.
6	Proof test is complete. Restore loop to full operation.



Table 10 Suggested Proof Test, 962

Step	Proof Test, Echotel Model 962 Loop				
-	(Refer to the Model 962 installation and operation manual and the SIL Safety Manual. Note the chart in the High/Low Dip Switch section of the I & O Manual.)				
1	Bypass the PLC or take other action to avoid a false trip.				
2	Inspect the Unit in detail outside and inside for physical damage or evidence of environmental or process leaks.				
	a. Inspect the exterior of the Unit housing. If there is any evidence of physical damage that may impact the integrity of the housing and the environmental protection, the unit should be repaired or replaced.				
	b. Inspect the interior of the Unit. Any evidence of moisture, from process or environment, is an indication of housing damage, and the unit should be repaired or replaced.				
3	Observe and record the settings of the HI/LOW and 22/3.6 DIP switches, the LED indicators, Loop Current and Sensor GAP conditions (WET or DRY).				
	If the FAULT condition is indicated by loop current and LED indicators all OFF, diagnose the fault and repair or replace the unit.				
	Confirm proper operation of the unit: WET/DRY GAP conditions; 8mA LED, 12mA or 16mA LED is lighted; Loop current = 8mA +/- 1mA, 12mA +/- 1mA or 16mA +/- 1 mA.				
	<ul> <li>a. Press LOOP TEST push button and confirm change;</li> <li>8mA &gt;&gt; 12mA, 12mA &gt;&gt; 16mA or 16mA &gt;&gt; 8mA.</li> <li>Release the button and unit returns to proper operation.</li> </ul>				
	b. Change HI/LOW DIP switch position. Confirm both LED & Loop Current change state; 8mA >> 16mA or 16mA >> 8mA . Note that 12mA will stay at 12mA with the switch change. Observe and record the time delay from change of DIP switch until LED and Loop current change. Delay is set by Time Delay Pot, so the delay may take somewhere around 10 seconds. Press LOOP TEST push button and confirm change; 8mA >> 12mA, 12mA >> 16mA or 16mA >> 8mA. Release the button and unit returns to proper operation. Change HI/LOW DIP switch back to original setting and confirm proper operation, after the delay.				
	c. Press FAULT TEST push button and confirm: all LEDs go OFF; Loop current $\ge 22$ mA or $\le 3.6$ mA based on 22/3.6 switch. Release button.				
	d. Change the 22/3.6 DIP switch position. Press FAULT TEST push button and confirm: all LEDs go OFF; Loop current $\geq$ 22mA or $\leq$ 3.6mA as expected. Release push button. Return 22/3.6 switch to original setting.				



	e. Adjust the Time Delay Pot to maximum delay, fully clock-wise up to 25 turns. Change HI/LOW DIP switch position and observe the time delay from change of DIP switch until LED and Loop current change. Confirm delay is ~10 seconds. Change HI/LOW DIP switch back to original setting and confirm ~10 seconds delay. Adjust the Time Delay Pot to minimum delay, fully counter-clock-wise ~25 turns. Change HI/LOW DIP switch position and observe the time delay. Confirm delay ≤ 1 second. Change HI/LOW DIP switch back to original setting and confirm switch back to original setting and confirm delay.
4	Move the process level to achieve three possible states: 1. both GAPs DRY, 2. one GAP DRY & one GAP WET, 3. Both GAPs WET. This test confirms operation with all GAP states.
	Confirm proper operation of the unit: WET/DRY GAP conditions; 8mA LED, 12mA or 16mA LED is lighted; Loop current = 8mA +/- 1mA, 12mA +/- 1mA or 16mA +/- 1 mA.
	a. Move the process level to achieve state 1. Both GAPS DRY. Confirm proper operation of the unit: WET/DRY GAP conditions; 8mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA or 16mA +/- 1 mA.
	b. Move the process level to achieve state 2. one GAP DRY and one GAP WET. Confirm proper operation of the unit: WET/DRY GAP conditions; 12mA LED is lighted; Loop current = 12mA +/- 1mA.
	c. Move the process level to achieve state 3. Both GAPS WET. Confirm proper operation of the unit: WET/DRY GAP conditions; 8mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA or 16mA +/- 1 mA.
	c. If unit fails the tests of steps 4.a 4.b or 4.c proceed to step 5.
	d. Adjust the Time Delay Pot to the original setting recorded in step 3b. Use HI/LOW DIP switch (just as you did in step 3b) to confirm that delay is returned to original setting.
F	e. Proceed to step 6.
5	If the unit under test fails to respond to process level changes remove the unit from the process and bench test.
	a. Remove the unit from the process. Inspect the ultrasound transducer for evidence of damage or coating buildup. Fouling on the transducer surface may interfere with normal operation. If heavy fouling is evident, it is suggested to service the transducer more frequently.
	b. Clean the ultrasonic transducer, especially in the area of the sensor GAPs.
	c. Perform a bench test per the steps of section 4. When possible it is best to use the actual process material, because material properties affect the ultrasonic performance. Confirm proper unit operation: WET/DRY GAP conditions; 8mA LED, 12mA LED or 16mA LED is lighted; Loop current = 8mA +/- 1mA, 12ma +/- 1mA or 16mA +/- 1 mA.



	d. If unit passes the tests of steps 5.c, return to the process installation and repeat the tests of step 4.	
	e. If the unit fails re-test in the process, it must be replaced.	
6	Proof test is complete. Restore loop to full operation.	



## B.2 Proof Test Coverage

The Proof Test Coverage for the various product configurations is given in Table 11.

### Table 11 Proof Test Coverage – 961/962

Device	λ <sub>DU</sub> PT	Proof Test Coverage	
	(FIT) <sup>6</sup>		
961Dry Is Safe	8	14.0%	
961 Wet Is Safe	10	64.6%	
962 Dry Is Safe	3	68.4%	
962 Wet Is Safe	6	86.3%	

<sup>&</sup>lt;sup>6</sup> This is the failure rate remaining after the proof test.



# Appendix C exida Environmental Profiles

<i>exida</i> Profile	1	2	3	4	5	6
Description (Electrical)	Cabinet mounted/ Climate Controlled	Low Power Field Mounted no self- heating	General Field Mounted self-heating	Subsea	Offshore	N/A
Description (Mechanical)	Cabinet mounted/ Climate Controlled	General Field Mounted	General Field Mounted	Subsea	Offshore	Process Wetted
IEC 60654-1 Profile	B2	C3 also applicable for D1	C3 also applicable for D1	N/A	C3 also applicable for D1	N/A
Average Ambient Temperature	30 C	25 C	25 C	5 C	25 C	25 C
Average Internal Temperature	60 C	30 C	45 C	5 C	45 C	Process Fluid Temp.
Daily Temperature Excursion (pk-pk)	5 C	25 C	25 C	0 C	25 C	N/A
Seasonal Temperature Excursion (winter average vs. summer average)	5 C	40 C	40 C	2 C	40 C	N/A
Exposed to Elements / Weather Conditions	No	Yes	Yes	Yes	Yes	Yes
Humidity <sup>7</sup>	0-95% Non- Condensing	0-100% Condensing	0-100% Condensing	0-100% Condensing	0-100% Condensing	N/A
Shock <sup>8</sup>	10 g	15 g	15 g	15 g	15 g	N/A
Vibration <sup>9</sup>	2 g	3 g	3 g	3 g	3 g	N/A
Chemical Corrosion <sup>10</sup>	G2	G3	G3	G3	G3	Compatible Material
Surge <sup>11</sup>						
Line-Line	0.5 kV	0.5 kV	0.5 kV	0.5 kV	0.5 kV	N/A
Line-Ground EMI Susceptibility <sup>12</sup>	1 kV	1 kV	1 kV	1 kV	1 kV	11/7
80 MHz to 1.4 GHz	10 V/m	10 V/m	10 V/m	10 V/m	10 V/m	
1.4 GHz to 2.0 GHz	3 V/m	3 V/m	3 V/m	3 V/m	3 V/m	N/A
2.0Ghz to 2.7 GHz	3 V/m 1 V/m	1 V/m	1 V/m	1 V/m	1 V/m	11//4
ESD (Air) <sup>13</sup>	6 kV	6 kV	6 kV	6 kV	6 kV	N/A

#### Table 12 exida Environmental Profiles

 <sup>&</sup>lt;sup>7</sup> Humidity rating per IEC 60068-2-3
 <sup>8</sup> Shock rating per IEC 60068-2-27
 <sup>9</sup> Vibration rating per IEC 60068-2-6
 <sup>10</sup> Chemical Corrosion rating per ISA 71.04
 <sup>11</sup> Surge rating per IEC 61000-4-5
 <sup>12</sup> EMI Susceptibility rating per IEC 61000-4-3



## Appendix D Determining Safety Integrity Level

The information in this appendix is intended to provide the method of determining the Safety Integrity Level (SIL) of a Safety Instrumented Function (SIF). The numbers used in the examples are not for the product described in this report.

Three things must be checked when verifying that a given Safety Instrumented Function (SIF) design meets a Safety Integrity Level (SIL) [N4] and [N7].

These are:

A. Systematic Capability or Prior Use Justification for each device meets the SIL level of the SIF;

B. Architecture Constraints (minimum redundancy requirements) are met; and

C. a PFD<sub>avg</sub> calculation result is within the range of numbers given for the SIL level.

A. Systematic Capability (SC) is defined in IEC61508:2010. The SC rating is a measure of design quality based upon the methods and techniques used to design and development a product. All devices in a SIF must have a SC rating equal or greater than the SIL level of the SIF. For example, a SIF is designed to meet SIL 3 with three pressure transmitters in a 2003 voting scheme. The transmitters have an SC2 rating. The design does not meet SIL 3. Alternatively, IEC 61511 allows the end user to perform a "Prior Use" justification. The end user evaluates the equipment to a given SIL level, documents the evaluation and takes responsibility for the justification.

B. Architecture constraints require certain minimum levels of redundancy. Different tables show different levels of redundancy for each SIL level. A table is chosen and redundancy is incorporated into the design [N8].

C. Probability of Failure on Demand ( $PFD_{avg}$ ) calculation uses several parameters, many of which are determined by the particular application and the operational policies of each site. Some parameters are product specific and the responsibility of the manufacturer. Those manufacturer specific parameters are given in this third party report.

A Probability of Failure on Demand ( $PFD_{avg}$ ) calculation must be done based on a number of variables including:

1. Failure rates of each product in the design including failure modes and any diagnostic coverage from automatic diagnostics (an attribute of the product given by this FMEDA report);

- 2. Redundancy of devices including common cause failures (an attribute of the SIF design);
- 3. Proof Test Intervals (assignable by end user practices);
- 4. Mean Time to Restore (an attribute of end user practices);

5. Proof Test Effectiveness; (an attribute of the proof test method used by the end user with an example given by this report);

6. Mission Time (an attribute of end user practices);

- 7. Proof Testing with process online or shutdown (an attribute of end user practices);
- 8. Proof Test Duration (an attribute of end user practices); and
- 9. Operational/Maintenance Capability (an attribute of end user practices).

The product manufacturer is responsible for the first variable. Most manufacturers use the *exida* FMEDA technique which is based on over 250 billion hours of field failure data in the process industries to predict these failure rates as seen in this report. A system designer chooses the second variable. All other variables are the responsibility of the end user site. The exSILentia®

<sup>&</sup>lt;sup>13</sup> ESD (Air) rating per IEC 61000-4-2



SILVer<sup>TM</sup> software considers all these variables and provides an effective means to calculate PFD<sub>avg</sub> for any given set of variables.

Simplified equations often account for only for first three variables. The equations published in IEC 61508-6, Annex B.3.2 [N1] cover only the first four variables. IEC61508-6 is only an informative portion of the standard and as such gives only concepts, examples and guidance based on the idealistic assumptions stated. These assumptions often result in optimistic  $PFD_{avg}$  calculations and have indicated SIL levels higher than reality. Therefore, idealistic equations should not be used for actual SIF design verification.

All the variables listed above are important. As an example consider a high level protection SIF. The proposed design has a single SIL 3 certified level transmitter, a SIL 3 certified safety logic solver, and a single remote actuated valve consisting of a certified solenoid valve, certified scotch yoke actuator and a certified ball valve. Note that the numbers chosen are only an example and not the product described in this report.

Using exSILentia with the following variables selected to represent results from simplified equations:

- Mission Time = 5 years
- Proof Test Interval = 1 year for the sensor and final element, 5 years for the logic solver
- Proof Test Coverage = 100% (ideal and unrealistic but commonly assumed)
- Proof Test done with process offline

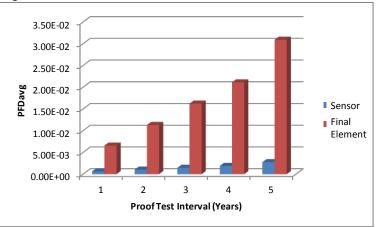
This results in a  $PFD_{avg}$  of 6.82E-03 which meets SIL 2 with a risk reduction factor of 147. The subsystem  $PFD_{avg}$  contributions are Sensor  $PFD_{avg} = 5.55E-04$ , Logic Solver  $PFD_{avg} = 9.55E-06$ , and Final Element  $PFD_{avg} = 6.26E-03$ . See Figure 2.



Navigation									
Safety Instrumented Function Results									
PFDavg Contribution	Achieved Safety Int	egrity Level			2				
Sensors     Logic Solver     Final Elements	Safety Integrity Le	vel (PFDavg)	2						
	Safety Integrity Le	vel (Architectural C	2						
	Safety Integrity Le	vel (Systematic Ca	2						
	Average Probability	of Failure on Dem	6.82E-03						
	Risk Reduction Fact	or (RRF)	147						
MTTFS Contribution  Mean Time to Failure Spurious (MTTFS) [years]					133.04				
Sensors     Logic Solver     Final Elements					SIL Limits				
		PFDavg	MTTFS [years]	SIL PFDavg					
					Arch. Const.	Sys. Cap.			
	Sensor Part	5.55E-04	620.76	2	2	2			
	Logic Solver Part	9.55E-06	1059.72		3	3			
	Final Element Part	6.26E-03	201.54		2	3			

Figure 2: exSILentia results for idealistic variables.

If the Proof Test Interval for the sensor and final element is increased in one year increments, the results are shown in Figure 3.



### Figure 3 PFD<sub>avg</sub> versus Proof Test Interval.

If a set of realistic variables for the same SIF are entered into the exSILentia software including:

- Mission Time = 25 years
- Proof Test Interval = 1 year for the sensor and final element, 5 years for the logic solver



- Proof Test Coverage = 90% for the sensor and 70% for the final element
- Proof Test Duration = 2 hours with process online.
- MTTR = 48 hours
- Maintenance Capability = Medium for sensor and final element, Good for logic solver

with all other variables remaining the same, the  $PFD_{avg}$  for the SIF equals 5.76E-02 which barely meets SIL 1 with a risk reduction factor 17. The subsystem  $PFD_{avg}$  contributions are Sensor  $PFD_{avg}$  = 2.77E-03, Logic Solver  $PFD_{avg}$  = 1.14E-05, and Final Element  $PFD_{avg}$  = 5.49E-02 (Figure 4).

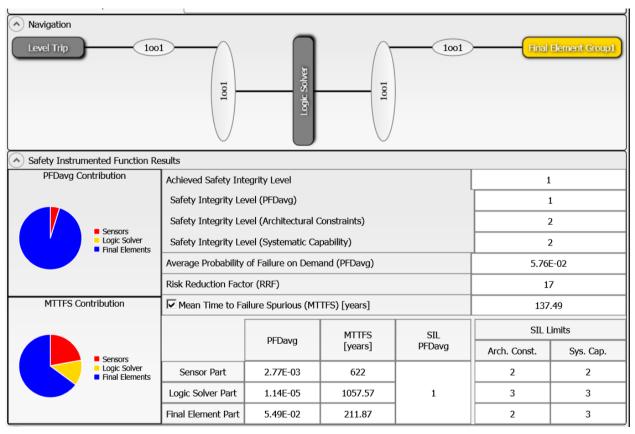


Figure 4: exSILentia results with realistic variables

It is clear that  $PFD_{avg}$  results can change an entire SIL level or more when all critical variables are not used.